

Title (en)
HIGH IMPEDANCE SUBSTRATE

Title (de)
SUBSTRAT MIT HOHER IMPEDANZ

Title (fr)
SUBSTRAT HAUTE IMPEDANCE

Publication
EP 1661206 B1 20061213 (FR)

Application
EP 04786396 A 20040830

Priority
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• FR 0350492 A 20030902

Abstract (en)
[origin: US7071876B2] A high-impedance substrate including a first layer made of insulating material, having a lower face and an upper face, the substrate including conductor patterns mechanically linked to the substrate. Some of the conductor patterns mechanically linked to the substrate are associated with a magnetic tile. At least one electrical interconnection puts two points distinct from one another of a conductor pattern mechanically linked to the substrate in electrical contact, this conductor pattern having an assigned magnetic tile, passing above the magnetic tile associated with the conductor pattern mechanically linked to the substrate.

IPC 8 full level
H01Q 15/00 (2006.01); **H01Q 7/06** (2006.01)

CPC (source: EP US)
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